



Material Content Data Sheet



Sales Product Name		BSC22DN20NS3 G		Issued		26. September 2017		
MA#		MA000862676						
Package		PG-TDSON-8-5		Weight*		118.72 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.916	0.77	0.77	7718	7718
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		318	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	copper	7440-50-8	37.762	31.81	31.85	318062	318476
wire	non noble metal	copper	7440-50-8	0.066	0.06	0.06	559	559
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		732	
	plastics	epoxy resin	-	6.173	5.20		51992	
	inorganic material	silicondioxide	60676-86-0	37.210	31.34	36.61	313414	366138
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12227	12227
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1394	1394
solder	noble metal	silver	7440-22-4	0.030	0.02		250	
	non noble metal	tin	7440-31-5	0.024	0.02		200	
	non noble metal	lead	7439-92-1	1.135	0.96	1.00	9563	10013
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.53	9.54	95347	95471
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		188	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	copper	7440-50-8	22.292	18.78	18.81	187760	188004
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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